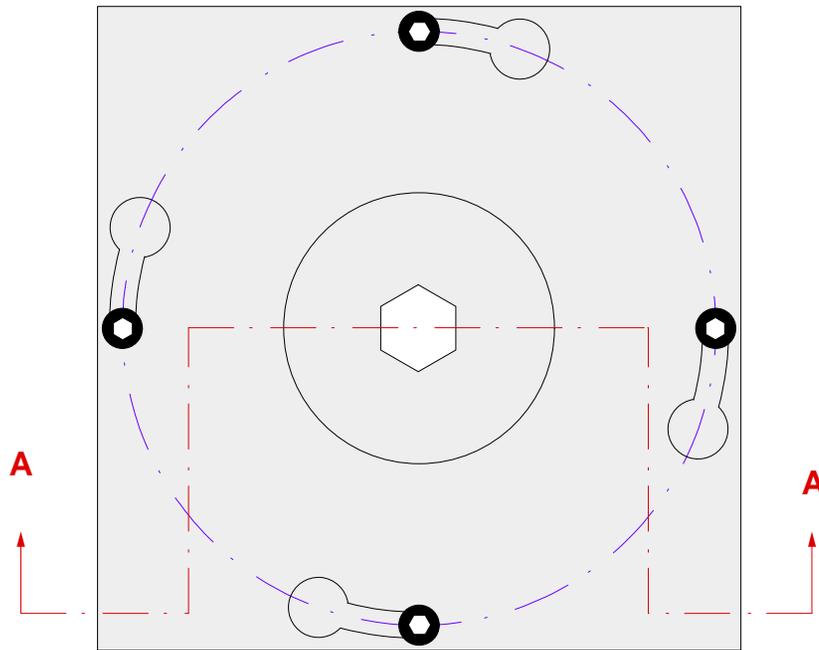


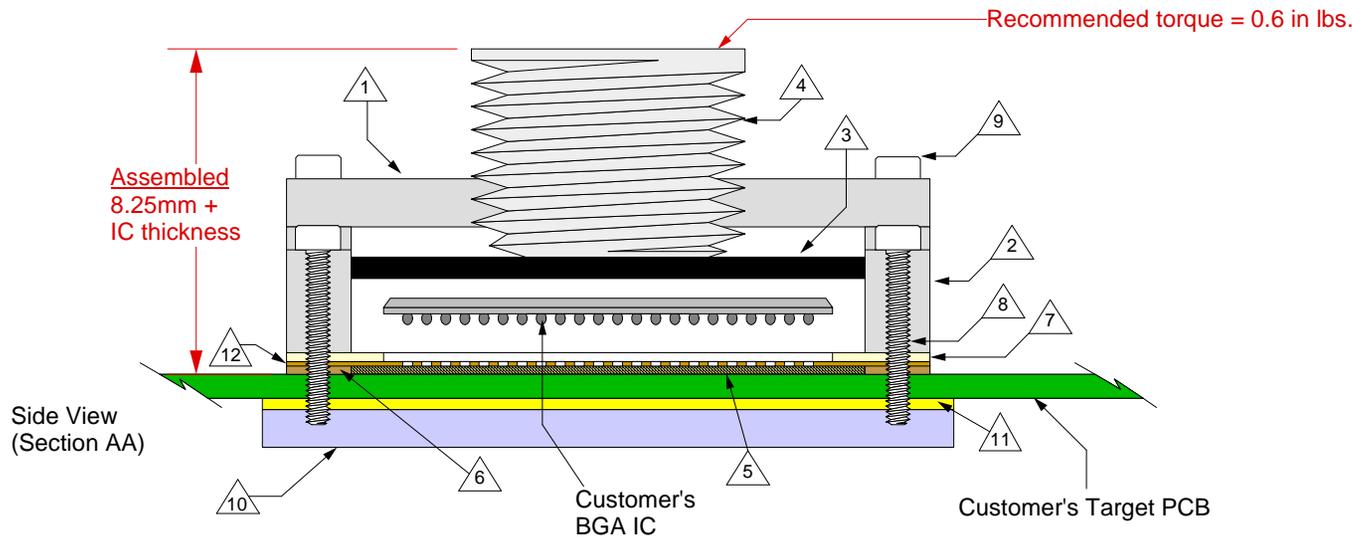
GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid



Top View



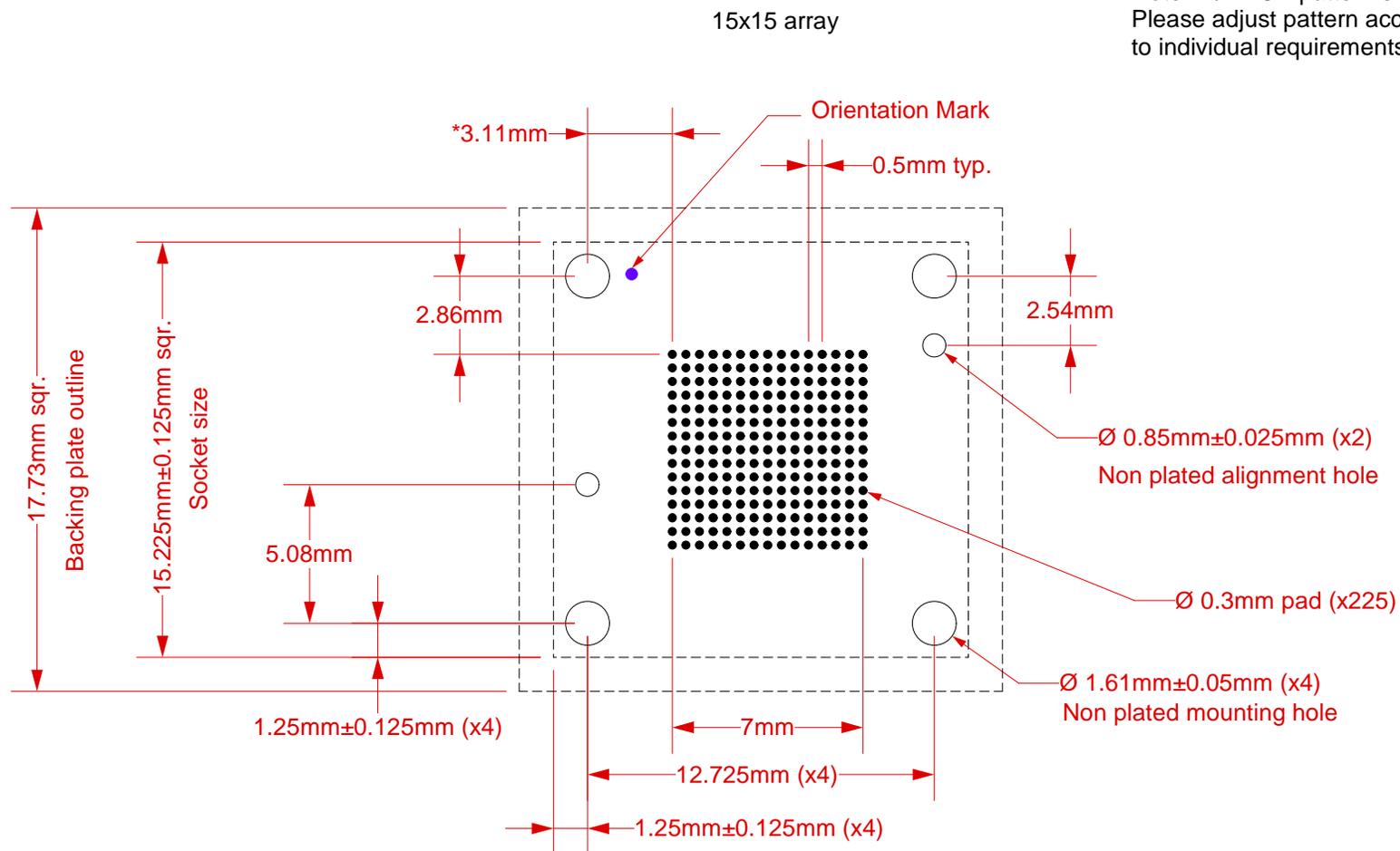
- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- △ 6 Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.
- △ 7 IC guide: Torton
- △ 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread , 9.525mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 Backing Plate: Aluminum. Thickness = 6.35mm
- △ 11 Insulating Plate: FR4. Thickness = 1.58mm.
- △ 12 Ball Guide: Kapton. Thickness = 0.003".

	SG-BGA-7044 Drawing	Status: Released	Scale: -	Rev: C
	© 2005 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: E Smolentseva		Date: 3/15/05
		File: SG-BGA-7044 Dwg.mcd	Modified: 11/14/14, DH	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**

Note: Full BGA pattern shown.
Please adjust pattern according to individual requirements.

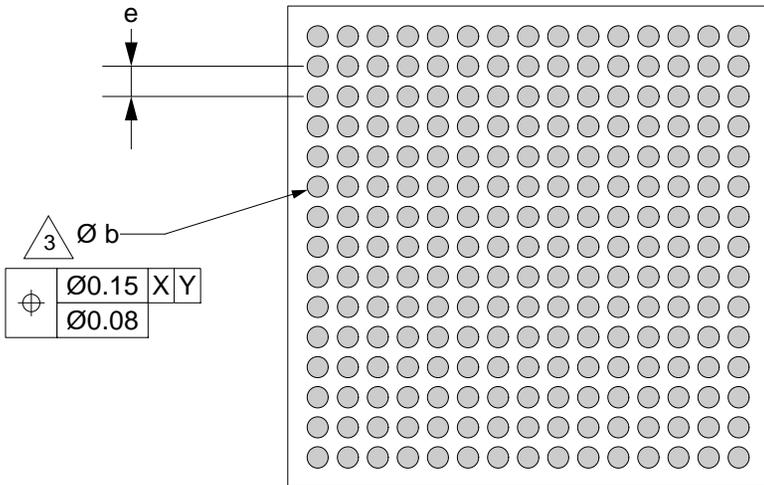
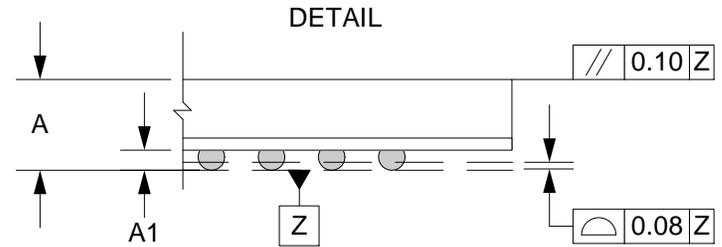
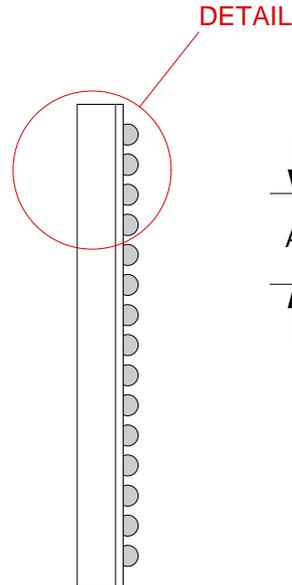
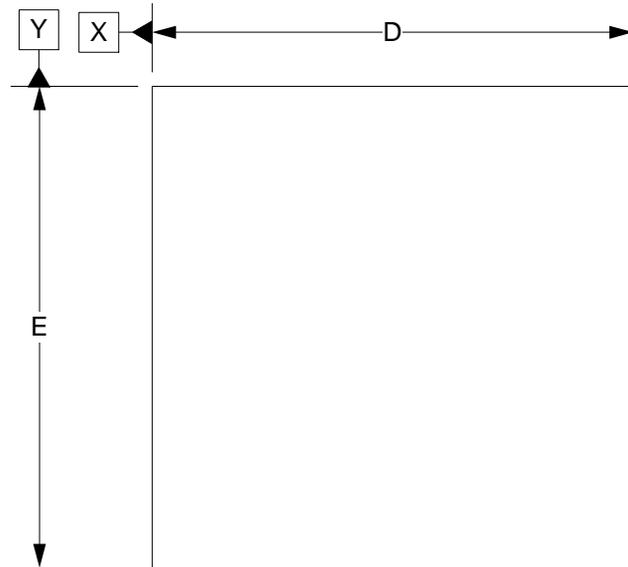


Target PCB Recommendations

Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

All dimensions are in mm unless stated otherwise
Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

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		Drawing: E Smolentseva		Date: 3/15/05
		File: SG-BGA-7044 Dwg.mcd		Modified: 11/14/14, DH



1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

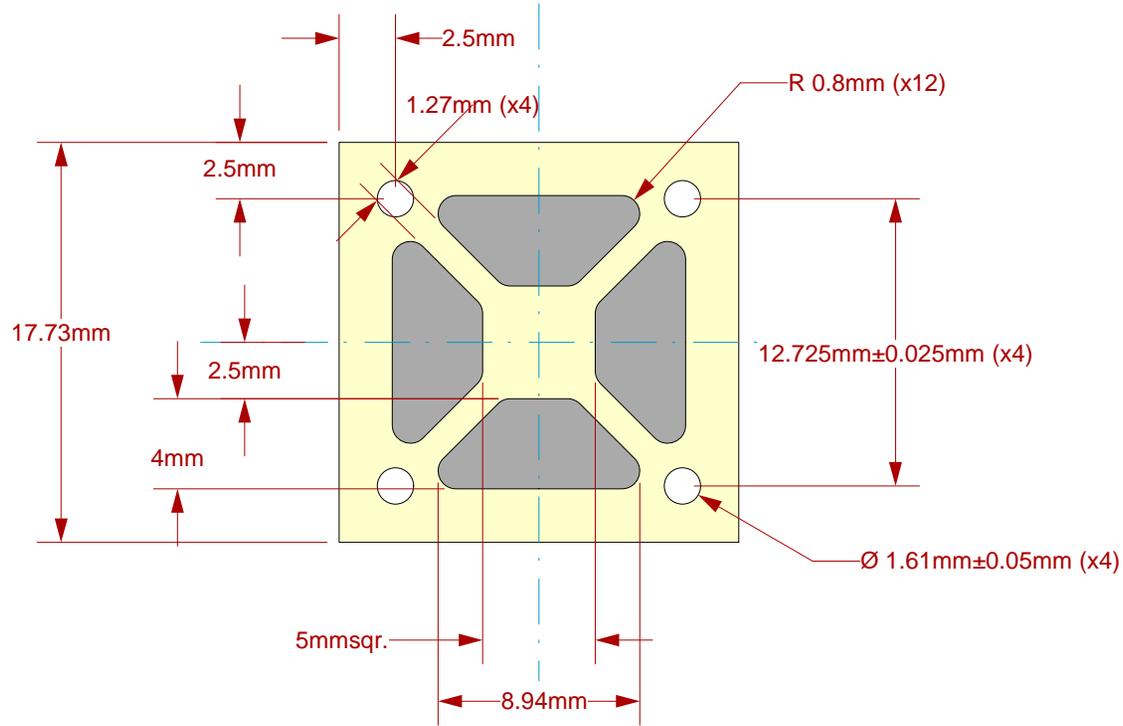
DIM	MIN	MAX
A		1.0
A1	0.15	0.25
b		0.38
D	8.0 BSC	
E	8.0 BSC	
e	0.5 BSC	

15 X 15 array

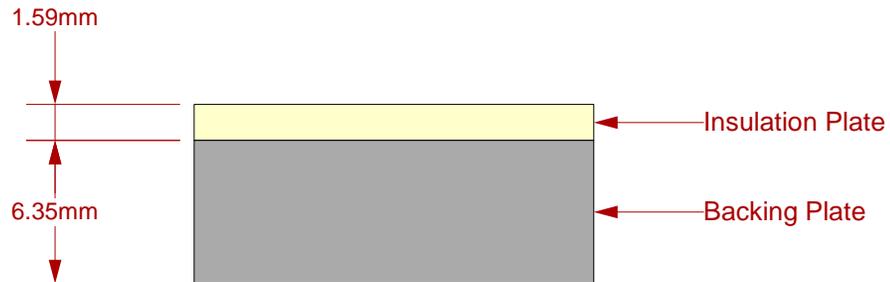
All dimensions are in mm unless stated otherwise

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	<p>Drawing: E Smolentseva</p>	<p>Date: 3/15/05</p>		
	<p>File: SG-BGA-7044 Dwg.mcd</p>	<p>Modified: 11/14/14, DH</p>		

Top View



Side View



All dimensions are in mm unless stated otherwise

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	<p>Drawing: E Smolentseva</p>	<p>Date: 3/15/05</p>		
	<p>File: SG-BGA-7044 Dwg.mcd</p>	<p>Modified: 11/14/14, DH</p>		